

e² studio Integrated Development Environment

Debugging Linux Applications Running on the R-Car (with the DTA as an Analysis Tool)

Introduction

This application note introduces the procedure for acquiring trace data of R-Car V4H through the command-line interface (CLI) of Linux which is running on an R-Car and displaying the data in the debug trace agent (DTA) trace window for use of the e² studio for R-Car.

Target Device

R-Car V4H

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1. Environment

The following lists the elements of the environment used in the descriptions in this application note.

Table 1-1 List of Environment Elements

Item	Detail	
R-Car V4H Reference Board	White Hawk	
	[RTP8A779G2ASKB0F10SA001]	
Host PC	Windows 10 (for use of the terminal display console or running Linux in a VirtualBox virtual environment)	
	Ubuntu 20.04 LTS (e² studio, TFTP server, or NFS server)	
e ² studio for R-Car	Version 2023-03	
	rcar-xos_tool_e2studio_ubuntu_2023-03.R20230313-1010.tar.gz	
R-Car V4H SDK	V3.12.0	
	rcar-xos_developer-adas-bootloader_v3.12.0_release.tar.gz	
	rcar-xos_platform-sdkX_v3.12.0_release.tar.gz (sample source code)	
R-Car V4H yocto Linux	V5.10.147	
(Kernel version)	rcar-xos_tool_yocto_linux_6.13.0.tar.gz	

This application note describes the procedure for using an environment in which a Linux environment has been set up for the R-Car on the reference board. For the procedure for setting up the Linux environment, refer to the user's manual included in the SDK.

2. Connection Diagram

Figure 2-1 shows a connection between the reference board for the R-Car V4H and a host PC. The IP addresses for use between the host PC and the reference board are set as shown in the figure. Specify the IP addresses which are to be set to suit the environment you are using.

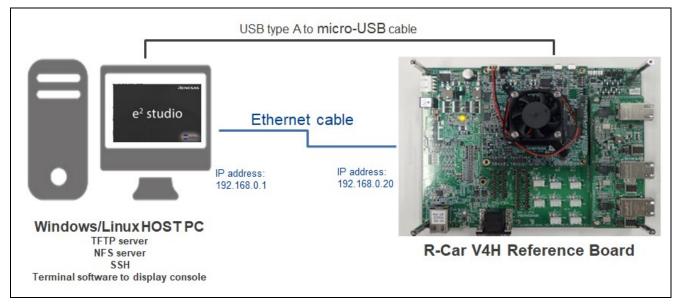


Figure 2-1 Connection between the Host PC and the Reference Board

3. Preparing Trace Data for the DTA

3.1 Starting Linux which Runs on an R-Car

Turn on the R-Car V4H and start Linux after reading an image for Linux running on an R-Car from the host PC.

The following shows the boot log messages in the serial console.

```
Using ethernet@e6800000 device
TFTP from server 192.168.0.1; our IP address is 192.168.0.20
Filename 'Image'.
Load address: 0x48080000
#############################
      4 MiB/s
done
Bytes transferred = 33839616 (2045a00 hex)
Using ethernet@e6800000 device
TFTP from server 192.168.0.1; our IP address is 192.168.0.20
Filename 'r8a779g0-whitehawk.dtb'.
Load address: 0x48000000
Loading: ########
      2.8 MiB/s
Done
```

Figure 3-1 Preparing Data (1)

After the image for Linux running on the R-Car has been started, log in to Linux to confirm its version.

```
After images of Linux running on R-Car has been started, log in Linux to confirm its version.

[ OK ] Started Target Communication Framework agent.

[ OK ] Started Avahi mDNS/DNS-SD Stack.

[ OK ] Reached target Multi-User System.

Starting Update UTMP about System Runlevel Changes...

[ OK ] Started Update UTMP about System Runlevel Changes.

Poky (Yocto Project Reference Distro) 3.1.11 v4x ttySCO

v4x login: root (Enter the password and press [Enter].)

root@v4x:~#

root@v4x:~# uname -a (Enter the command and press [Enter].)

Linux v4x 5.10.147-yocto-standard #1 SMP PREEMPT Fri Mar 3 11:25:12 UTC 2023 aarch64 aarch64 GNU/Linux

root@v4x:~#
```

Figure 3-2 Preparing Data (2)

3.2 Preparing an Executable File for Acquiring Trace Data

When the e^2 studio is installed on the host PC, a pre-constructed stub file is stored in the DebugComp/RCar directory of the e^2 studio. The path name is given below.

"/home/<user name>/.eclipse/com.renesas.platform XXXXXXXXXX/DebugComp/RCar"

Figure 3-3 Preparing Data (3)

Select "perfmodule.ko" and "saperfmon.elf" corresponding to the version of Linux running on the R-Car and the target board. Store these files in the desired working directory of Linux.

Note that the following files are used in this environment.

```
impsample_core_link (sample application for adding DTA messages to the trace data)
perfmodule.ko (file for operating an elf file)
saperfmon.elf (executable file for acquiring trace data)
```

Figure 3-4 Preparing Data (4)

Store the files in the desired directory of Linux running on the R-Car and assign the executable right to the files to be executed.

Figure 3-5 Preparing Data (5)

Notes:

- The sample application (impsample_core_link) uses a sample file (rcar-xos/v3.12.0/samples/impsample_core_link/) included in the SDK.
- The perfmodule.ko and saperfmon.elf files are rebuilt after some source code has been changed with reference to "DTA_guide.pdf" in the support directory for performance-monitor (/home/<user name>/.eclipse/com.renesas.platform_XXXXXXXXXXX/DebugComp/RCar/performance-monitor).

The performance-monitor directory is generated by starting the e² studio on the host PC, creating the R-Car project, and proceeding with debugging.

Select [File] -> [New] -> [Renesas C/C++ Project] -> [Renesas R-Car] to open the [New C/C++ Project] dialog box.

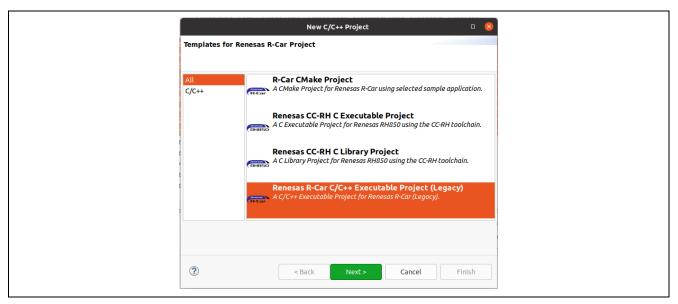


Figure 3-6 Preparing Data (6)

Select "Hello World" as a simple project and click on the [Next] button.

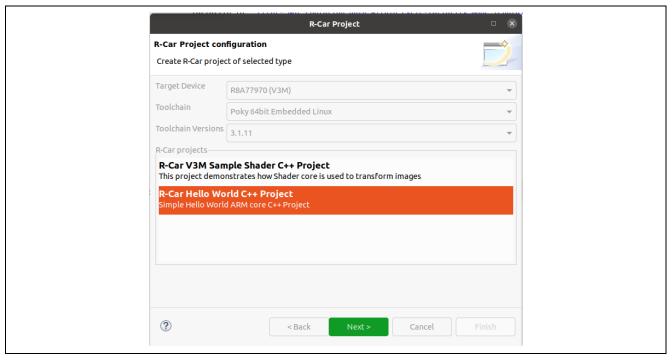


Figure 3-7 Preparing Data (7)

Enter the desired project name and click on the [Finish] button.

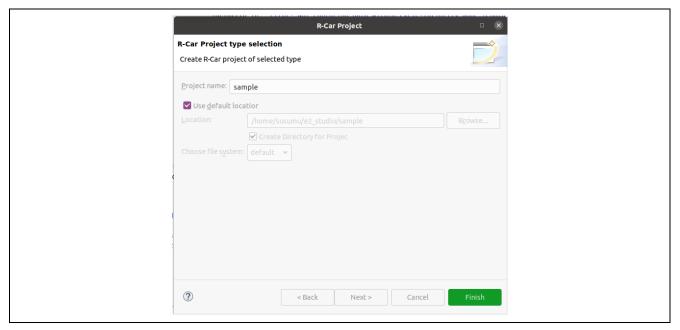


Figure 3-8 Preparing Data (8)

When the created project is displayed in the list of projects, start debugging. Even if debugging fails to start, a support directory for performance-monitor will be generated under "~/DebugComp/RCar". Refer to "DTA_guide.pdf".

For the path to the support directory, open the [About e² studio for R-Car] dialog box and click on the [Installation Details] button by selecting the [About e² studio for R-Car] item from the [Help] menu.

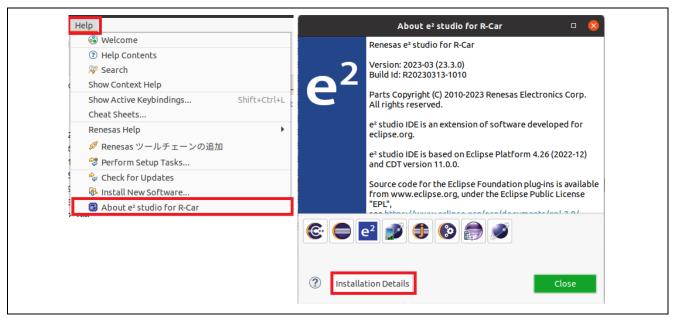


Figure 3-9 Preparing Data (9)

The [e² studio for R-Car Installation Details] window will open. Selecting the [Support Folders] tab enables confirmation of the path to the support directories.



Figure 3-10 Preparing Data (10)

3.3 Starting the DTA in Each Available Mode

Start the DTA in the desired working directory of Linux running on the R-Car.

3.3.1 Loading a Module for Operating an elf File

Before starting the DTA, load a module. If an attempt is made to load a module that has already been loaded, an error message will be displayed.

*To unload a module, run the rmmod command.

```
root@v4x:~/XXXXXXXX# insmod ./perfmodule.ko (Enter the command and press [Enter].)
[ 9382.722569] Perfmodule - Board Type V4H detected (0x5c12)
root@v4x:~/XXXXXXXX#
root@v4x:~/XXXXXXXX# insmod ./perfmodule.ko (Enter the command and press [Enter].)
insmod: ERROR: could not insert module ./perfmodule.ko: File exists
root@v4x:~/XXXXXXXX#
```

Figure 3-11 Preparing Data (11)

Operating an elf File for Viewing RAW Messages without Event Matching

When the <-em0> option is specified for the executable file for acquiring trace data (saperfmon.elf), the trace YYYYMMDD HHMMSS directory is created so that tracing can start. After that, the sample application (impsample_core_link) is executed.

```
\verb|root@v4x:~/XXXXXXX# ./saperfmon.elf -em0 & (Enter the command and press [Enter].)|\\
\verb"root@v4x:~/XXXXXXX# Current working dir: /home/root/XXXXXXXX (desired directory name)"
uio PMU driver 1 auto-detection: /dev/uio369
uio DBSC driver auto-detection: /dev/uio368
uio QOS driver auto-detection: /dev/uio367
Trace directory: /home/root/XXXXXXXX/trace YYYYMMDD HHMMSS
QOS Flat Event Summary
_____
0 - Merge_int(W)
1 - Secure engine (W)
V4H config end, reading thread started.
Time translation sent back.
Time translation sent back.
root@v4x:~/XXXXXXX# ./impsample core link (Enter the command and press [Enter].)
<IMP Framework Demo start>
RCAR SOC
            V4H
ATMLIB Version 2.20.0
IMPFW Version 3.12.0
Execute IMP with IMP core and PSC core
-- OutPutMemory Image data of SPM --
00 00 00 00 04 00 00 00 08 00 00 00 0C 00 00 00
F0 10 F4 10 F8 10 FC 10
[RESULT] PASS
<IMP Framework Demo end>
impsample_core_link return = 0 (OK:0, NG:else)
root@v4x:~/e2studio#
```

Figure 3-12 **Preparing Data (12)**

3.3.3 Operating an elf File with Event Matching

When the <-em1> option is specified for the executable file for acquiring trace data (saperfmon.elf), the trace_YYYYMMDD_HHMMSS directory is created so that tracing can start. After that, the sample application (impsample_core_link) is executed.

```
root@v4x:~/XXXXXXX# ./saperfmon.elf -em1 & (Enter the command and press [Enter].)
    :
root@v4x:~/XXXXXXXX# ./impsample_core_link (Enter the command and press [Enter].)
    :
root@v4x:~/XXXXXXXX#
```

Figure 3-13 Preparing Data (13)

3.3.4 Operating an elf File with Event Matching, QoS Monitoring, and 1-s Sampling Rate (100000 * 10 us)

When the <-qevt>, <40, 41, 42, 43 (master of CCIO-4)>, and <-s 100000> options are specified for the executable file for acquiring trace data (saperfmon.elf), the trace_YYYYMMDD_HHMMSS directory is created so that tracing can start. After that, the sample application (impsample core link) is executed.

```
root@v4x:~/XXXXXXXX# ./saperfmon.elf -qevt 40,41,42,43 -s 100000 & (Enter the command and press [Enter].)

:
root@v4x:~/XXXXXXXX# ./impsample_core_link (Enter the command and press [Enter].)

:
root@v4x:~/XXXXXXXX#
```

Figure 3-14 Preparing Data (14)

Notes:

 You can confirm that the DTA messages have been added in trace.txt within the trace_YYYYMMDD_HHMMSS directory.

```
:
DTA EM: 0x11 0x02 0x00 0x00 0x01 0x0F, printf: , TS: 0x0000000539D08387, EpochTS: 1677858023804397383
DTA EM: 0x11 0x02 0x00 0x00 0x01 0x0F, printf: , TS: 0x0000000539D083A3, EpochTS: 1677858023804400743
DTA RAW: 0x10 TS: 0x0000000539D098DB, EpochTS: 1677858023805052583
DTA RAW: 0x10 TS: 0x0000000539D098DB, EpochTS: 1677858023805052583
:
```

Figure 3-15 Preparing Data (15)

 You can also confirm that the stream_XXX files have been added within the trace_YYYYMMDD_HHMMSS directory.

Figure 3-16 Preparing Data (16)

If you execute the sample application (impsample_core_link) after you have executed "saperfmon.elf", an
error may occur. In such cases, repeat the attempt to execute the application up to about ten times until it
starts.

Figure 3-17 Preparing Data (17)

4. Operations for Debugging

4.1 Creating a "Tracing" Project

Start the e² studio on the host PC and create a "Tracing" project.

Select [File] -> [New] -> [Project...] to open the [New Project] dialog box.

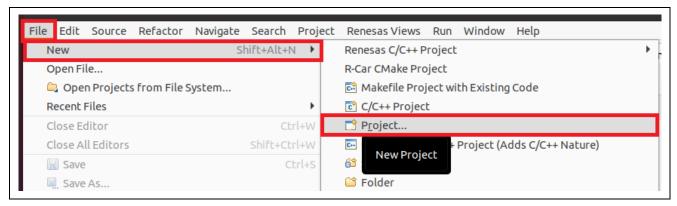


Figure 4-1 Operation for Debugging (1)

Select [Tracing Project] in the [New Project] dialog box and click on the [Next] button.

The [Tracing Project] dialog box appears. Enter the desired project name and click on the [Finish] button.

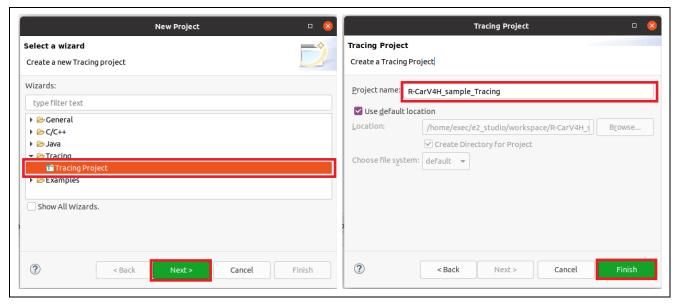


Figure 4-2 Operation for Debugging (2)

4.2 Setting Trace Profiling

Select "Fetch Remote Traces..." from the trace project with the desired name to open the [Fetch Remote Traces] dialog box.

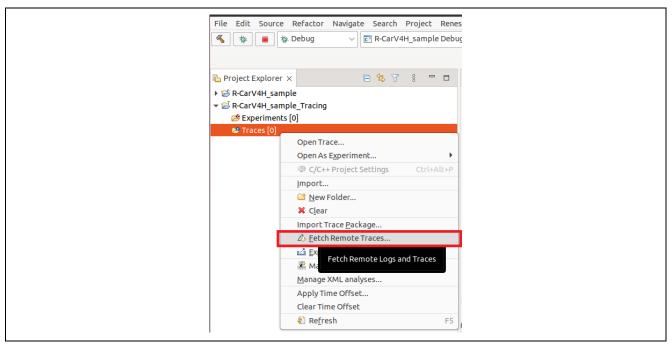


Figure 4-3 Operation for Debugging (3)

Click on the [Manage Profiles] button to open the [Preferences (Filtered)] dialog box.

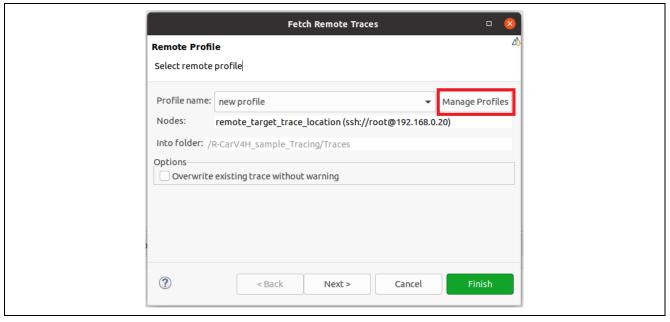


Figure 4-4 Operation for Debugging (4)

In the [Preferences (Filtered)] dialog box, set the trace profiling for the SSH connection as shown in the figure below.

- URI: Specify the root user name and IP address of the target (R-Car V4H reference board).
- Root path: Specify the desired directory of Linux running on the R-Car for use in remote tracing.
- Recursive: Select the checkbox.
- Trace type: Select the "R-Car Performance Trace" format.

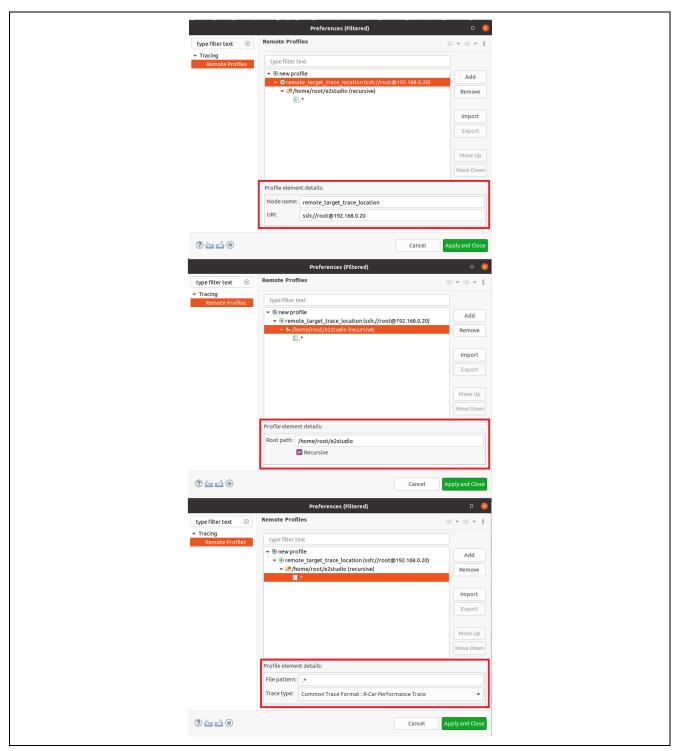


Figure 4-5 Operation for Debugging (5)

Click on the [Apply and Close] button in the [Preferences (Filtered)] dialog box to return to the [Fetch Remote Traces] dialog box.

4.3 Importing Trace Data

Click on the [Next] button in the [Fetch Remote Traces] dialog box.

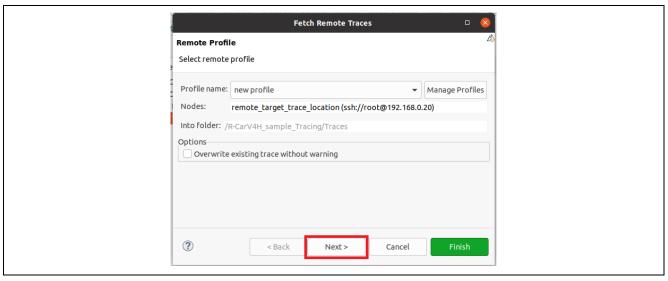


Figure 4-6 Operation for Debugging (6)

Select the required trace type and import all items except for the text log. After that, click on the [Finish] button.

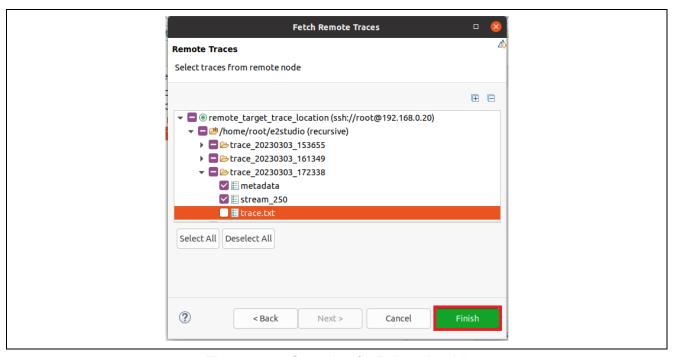


Figure 4-7 Operation for Debugging (7)

4.4 Displaying Trace Data

A trace directory is displayed in the trace project. Right-click on the name of the trace directory and specify "R-Car Performance Trace" as the trace type.

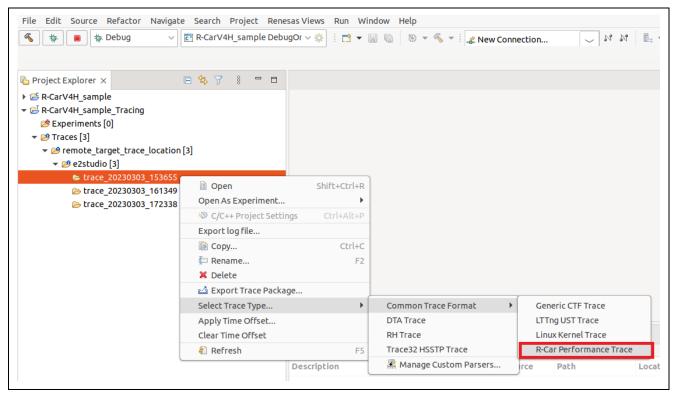


Figure 4-8 Operation for Debugging (8)

Double-clicking on the "trace_YYYYMMDD_HHMMSS" directory in the trace project displays a list of tracing operations.

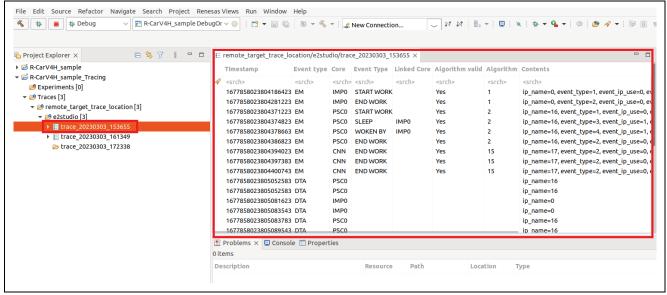


Figure 4-9 Operation for Debugging (9)

Double-clicking on "System Performance – DTA Trace" in the trace project opens the view for the DTA.

The content of tracing selected from the list of tracing operations is displayed in the view.

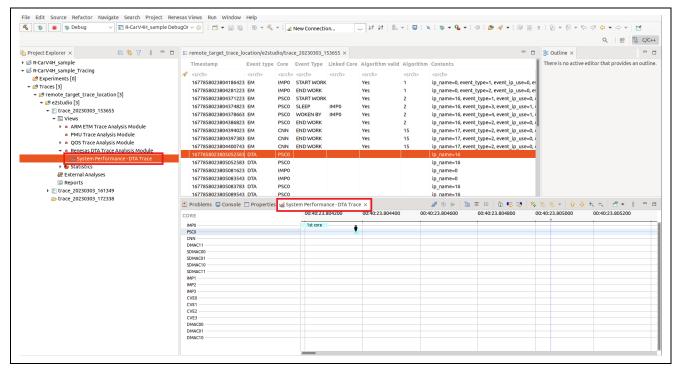


Figure 4-10 Operation for Debugging (10)

The [Show View] dialog box is opened by selecting [Window] -> [Show View] -> [Other...]. Selecting [Renesas R-Car Trace] -> [System Performance – DTA] and clicking on the [Open] button also opens the view for the DTA.

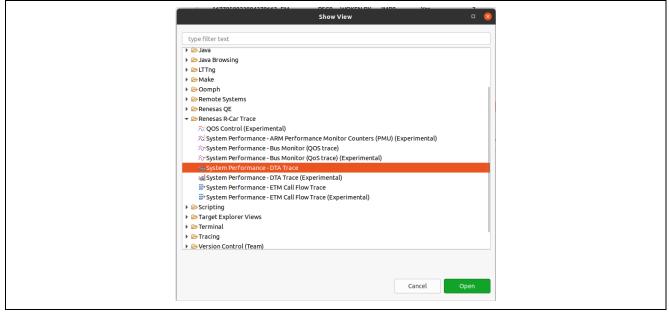


Figure 4-11 Operation for Debugging (11)

Revision History

		Description		
Rev.	Date	Page	Summary	
1.00	Oct.31.23	-	First Edition issued	

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2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

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